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Bridging the Gap in Advanced Packaging

XTPL's Additive Manufacturing Solution for Heterogeneous Integration and Chiplet Assembly

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XTPL SA

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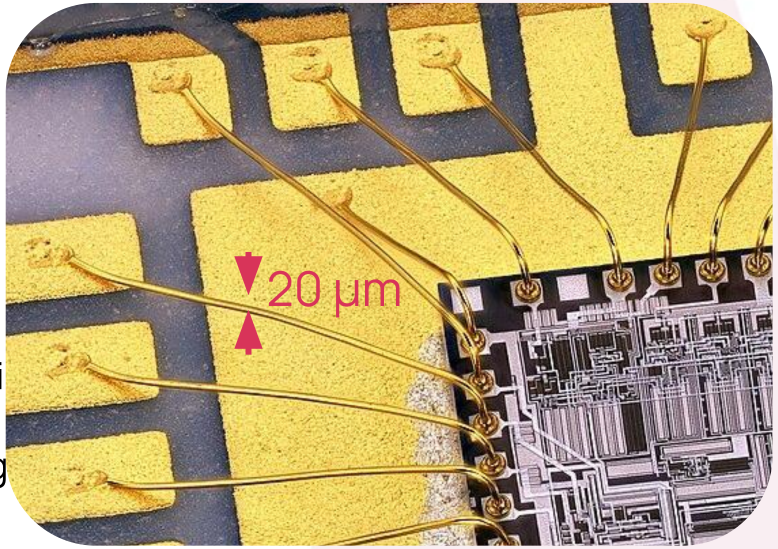
Company at a glance

- Locations: Wrocław (Poland) – headquaters, Boston, MA – sales and support office
- Interdisciplinary team of 70, 25% of the team with PhDs
- 10 distributing partners globally
- 45 granted patents
- Technology: Ultra-Precise Dispensing (UPD) – maskless additive deposition of nanomaterials at 1 to 10 µm resolution
- Products: Delta Printing System (R&D platform), UPD Modules (industrial integration), High-Performance Materials
- Target Applications: interconnects for heterogeneous integration and circuit editing, microbump dispensing, via filling for advanced packaging
- Target Markets: Semiconductor & Advanced Packaging, HealthTech, Flat Panel Displays
- Contact: piotr.kowalczewski@xtpl.com, www.xtpl.com



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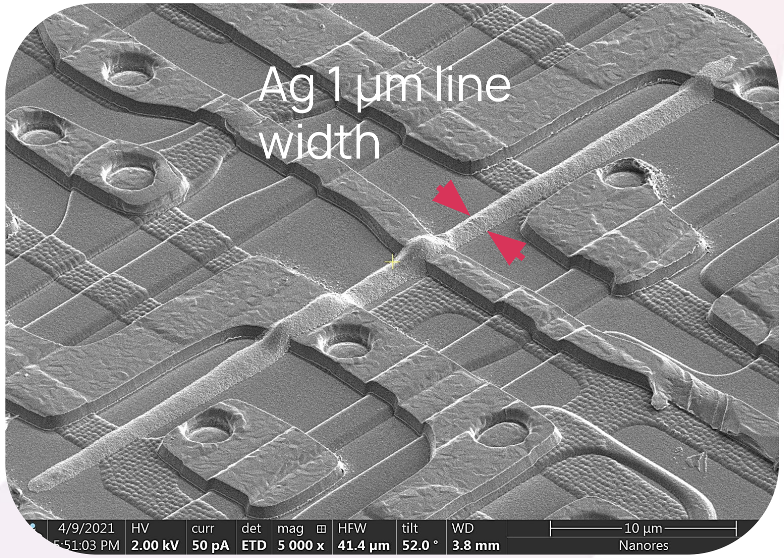
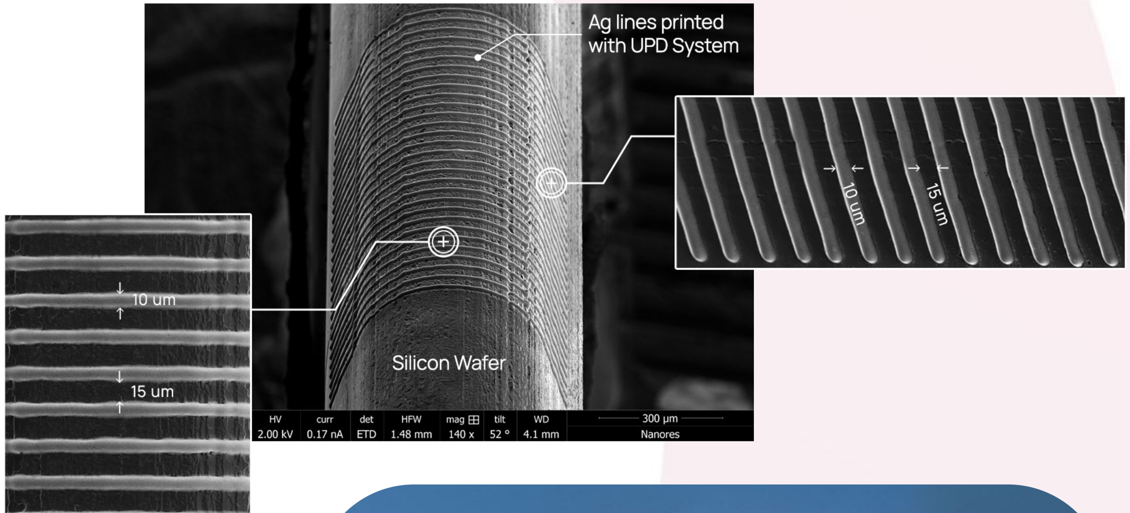
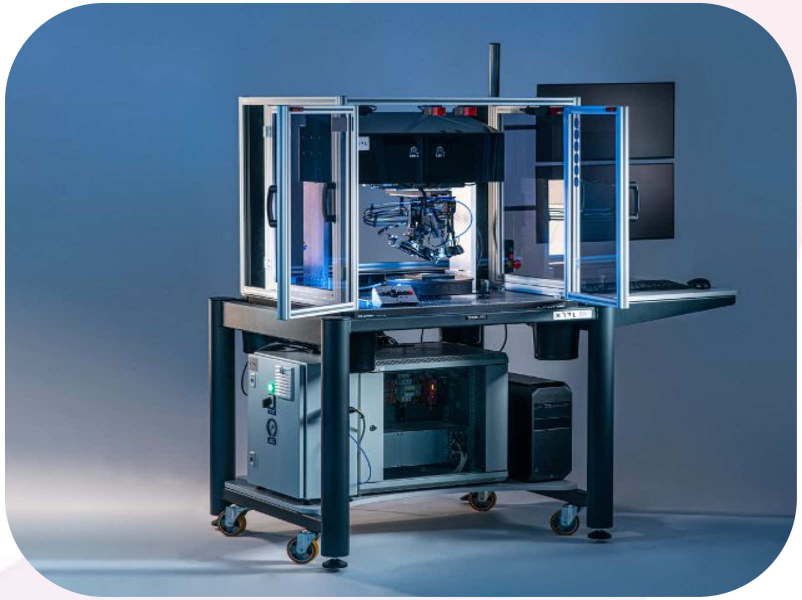


XTPL
Ultra-Precise
Dispensing

Company’s Activities

- Previous experience with collaborative projects:
  - Horizon Europe: “ULTRASENSE” (partner)
  - Horizon Europe: “MicroLED Displays by Additive Manufacturing” (partner)
- Interactions with one of the 3IAs or other ETPs:
  - Member of EPoSS
  - Frequent participation in excellent EPoSS events





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Collaboration Expectations

Collaborative project of interest to you	*Chips JU, Horizon Europe*
Scope	*Providing Ultra-Precise Dispensing (UPD) technology and high-performance materials to consortium partners.*
Project idea	*Advanced packaging, heterogeneous integration, failure analysis and circuit editing.*
Project impact	*Enabling cost-effective, maskless micro-fabrication for advanced packaging and heterogeneous integration to strengthen European manufacturing capabilities.*
Project consortium	*We are searching for SME and academic partners offering expertise in advanced packaging, heterogeneous integration, and failure analysis.*